

Appl. No. 10/623,815  
Amdt. dated 7/12/06  
Reply to Office action of 4/14/06

CLAIM AMENDMENTS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended). A semiconductor component comprising:

a semiconductor chip including an electronic circuit configured in said semiconductor chip, said electronic circuit having a terminal for a signal to be processed, a stage connected to said terminal for the signal, a terminal for obtaining a supply potential, said terminal for obtaining the supply potential being connected to said stage, said stage being selected from a group consisting of an input stage and an output stage;

a first conductor track running outside said semiconductor chip, said first conductor track being connected to said terminal for the signal;

a second conductor track running outside said semiconductor chip, said second conductor track being connected to said terminal for obtaining the supply potential;

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a further conductor track running outside ~~the entire~~  
~~components/circuits/stages of~~ said semiconductor chip, said  
further conductor track being connected to said second  
conductor track, said further conductor track entirely  
surrounding said semiconductor chip, said further conductor  
track crossing said first conductor track, defining a  
crossing location, and said further conductor track crossing  
said second conductor track; and

an electrostatic discharge protection element for carrying an  
electrostatic discharge away from said terminal for the  
signal and to the supply potential, said electrostatic  
discharge protection element being disposed outside of said  
semiconductor chip, said electrostatic discharge protection  
element being connected outside of said semiconductor chip to  
said further conductor track and to said first conductor  
track, said electrostatic discharge protection element being  
disposed close to said crossing location.

Claim 2 (previously presented). The semiconductor component  
according to claim 1, further comprising:

a package surrounding said semiconductor chip and said  
further conductor track;

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said package partially surrounding said first conductor track such that a portion of said first conductor track facing toward said semiconductor chip runs inside said package and a portion of said first conductor track facing away from said semiconductor chip runs outside said package; and

said package partially surrounding said second conductor track such that a portion of said second conductor track facing toward said semiconductor chip runs inside said package and a portion of said second conductor track facing away from said semiconductor chip runs outside said package.

Claim 3 (previously presented). The semiconductor component according to claim 1, wherein:

said electrostatic discharge protection element is a diode;

said diode has an anode connected to said further conductor track; and

said diode has a cathode connected to said first conductor track.

Claim 4 (canceled)...

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Claim 5 (original). The semiconductor component according to claim 4, further comprising an insulation material configured where said further conductor track crosses said first conductor track.

Claim 6 (previously presented). The semiconductor component according to claim 1, further comprising:

a third conductor track;

a terminal for a signal and assigned to said third conductor track; and

a further electrostatic discharge protection element;

said further conductor track running in a main direction and having a conductor track portion branching away from said main direction;

said third conductor track crossing said further conductor track near said conductor track portion of said further conductor track, defining a further crossing location; and

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said conductor track portion of said further conductor track  
is connected to said further electrostatic discharge  
protection element.

Claim 7 (original). The semiconductor component according to  
claim 1, further comprising:

a bonding wire connecting said first conductor track to said  
terminal for the signal; and

a bonding wire connecting said second conductor track to said  
terminal for obtaining the supply potential.

Claim 8 (previously presented). The semiconductor component  
according to claim 7, wherein said terminal for the signal  
and said terminal for obtaining the supply potential are  
metallized areas configured in said semiconductor chip.

Claim 9 (original). The semiconductor component according to  
claim 1, wherein:

said input stage has at least one transistor with a gate  
connected to said terminal for the signal;

said transistor has a drain terminal and a source terminal;

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said drain terminal or said source terminal of said transistor connected to said terminal for the supply potential.

Claim 10 (original). The semiconductor component according to claim 9, wherein said input stage is an inverter.

Claim 11 (previously presented). The semiconductor component according to claim 1, further comprising a leadframe disposed outside said semiconductor chip and including said first conductor track, said first conductor track having a contact area connected to a terminal of said electrostatic discharge protection element.

Claim 12 (previously presented). The semiconductor component according to claim 1, wherein said first conductor track is connected to said terminal for the signal through a bonding wire.

Claim 13 (previously presented). The semiconductor component according to claim 6, wherein said further electrostatic discharge protection element is disposed at said further crossing location.